

providing an insulation film having two rows of sprocket holes comprising a plurality of sprocket holes formed at a pitch L along both edges of the insulation film; and

forming a two-dimensional array of through holes in said insulation film between the rows of sprocket holes, each through hole in said array spaced from adjacent through holes by a pitch p .

8. (twice amended) The method for manufacture of an insulation film according to claim 6 wherein the method further comprises a step of forming a two-dimensional array of circuit patterns upon the insulation film according to size of the semiconductor package and a for-plating-electricity-supply-use conductor pattern electrically connected with the array of circuit patterns.

9. (twice amended) A method for manufacture of a semiconductor package comprising the steps of: providing an insulation film, forming two rows of sprocket holes comprising a plurality of sprocket holes formed at a pitch L along both edges of the insulation film, forming a two-dimensional array of through holes between the rows of sprocket holes, each through hole in said array spaced from adjacent through holes by a pitch p , forming a two-dimensional plurality of circuit patterns upon the insulation film according to size of the semiconductor package, forming a for-plating-electricity-supply-use conductor pattern electrically connected with the plurality of circuit patterns having a main line surrounding a perimeter of the plurality of circuit patterns and a sub-line electrically connecting each of the circuit patterns to the main line;

mounting a semiconductor chip within a respective prescribed region of each circuit pattern of the insulation film and electrically connecting the semiconductor chip with the circuit pattern;

performing resin sealing for partitioning off each region enclosed by the main line of the conductor pattern; and

cutting apart into individual semiconductor packages by dicing along the sub-lines of the insulation film.

12. (twice amended) The method for manufacture of an insulation film according to claim 7 wherein the method further comprises a step of forming a two-dimensional array of circuit patterns upon the insulation film according to size of the semiconductor package and a for-plating-electricity-supply-use conductor pattern electrically connected with the plurality of circuit patterns.

14. (amended) A method of packaging a semiconductor device, comprising the steps of:

providing an insulation film having rows of sprocket holes at a pitch L along the edges of said film and a two-dimensional array of through holes in said film between the rows of sprocket holes, said through holes arranged relative to one another in said array at a pitch p ;

mounting a semiconductor chip over a number of said through holes;

sealing said semiconductor chip and a portion of said insulation film in resin; and

cutting said insulation film surrounding said semiconductor chip to release said resin-sealed chip from the remainder of said insulation film.

15. (amended) The method of Claim 14, wherein said step of providing an insulation film comprises:

providing an insulation film having rows of sprocket holes at a pitch L along the edges of said film, and a two-dimensional array of through holes in said film between the rows of sprocket holes, said through holes arranged relative to one another in said array at a pitch p and continuously along and transversely across said film within circuit pattern regions on said film.

17. (amended) The method of Claim 14, wherein said step of providing an insulation film comprises:

providing an insulation film having rows of sprocket holes at a pitch L along the edges of said film, and a two-dimensional array of through holes in said